

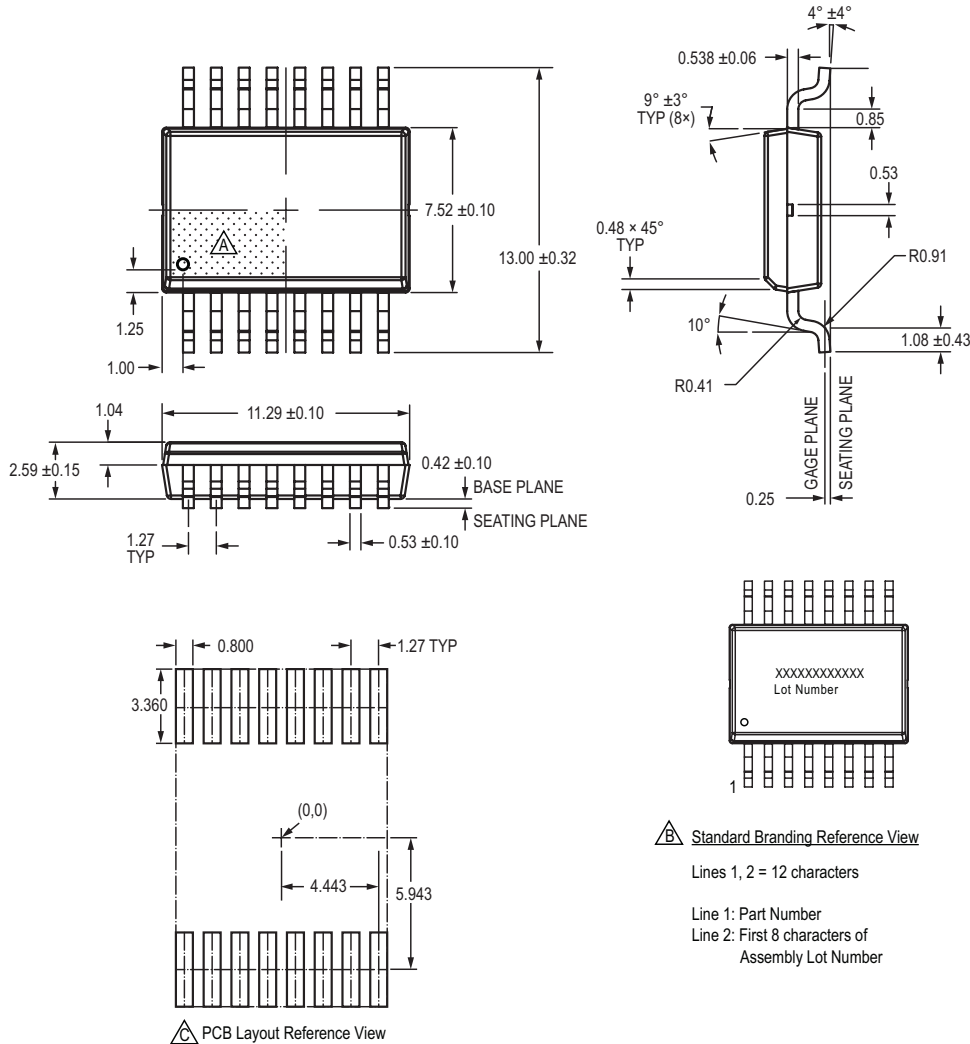
For Reference Only; Not for Tooling Use


(reference DWG-0000714, Rev. 2)

Dimensions in millimeters


Dimensions exclusive of mold flash, gate burrs, and dambar protrusions

Exact case and lead configuration at supplier discretion within limits shown



 Terminal #1 mark area

 Branding scale and appearance at supplier discretion

 Reference land pattern layout; all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)